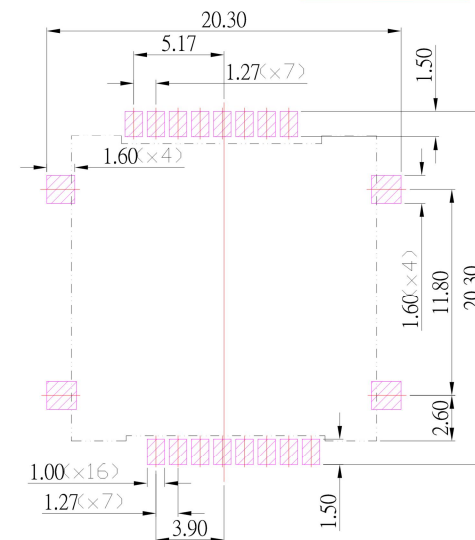
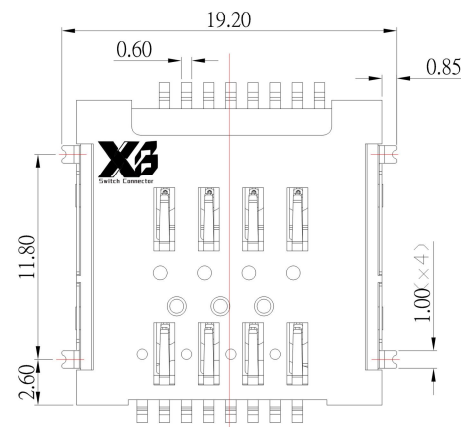
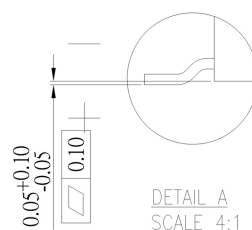
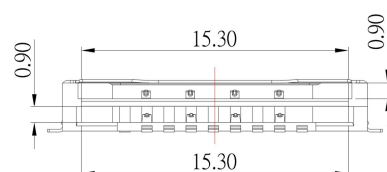
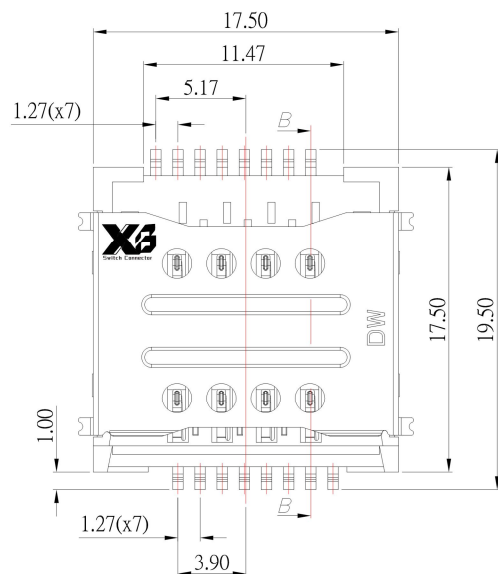


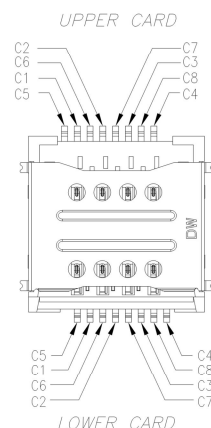
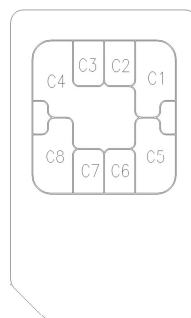
SECTION B-B



P.C.B LAYOUT MOUNTING PATTERN

C1	C1:VCC
C2	C2:RST
C3	C3:CLK
C4	C4:RESERVED
C5	C5:GND
C6	C6:VPP
C7	C7:I/O
C8	C8:RESERVED

SIM CARD CIRCUIT



MATERIALS:

1. HOUSING : HIGH TEMPERATURE THERMOPLASTIC
2. CONTACT : COPPER ALLOY
3. SHELL : SUS

Finish:

1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
TIN PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

1. INSULATION RESISTANCE : 1000M Ω MIN.
2. CONTACT RESISTANCE : 50m Ω MAX.
3. Dielectric Withstanding Voltage: 350V AC
4. Durability: 3000 cycles



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DONG GUAN XI BANG ELECTRONICS CO., LTD.

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ± 0.2
Above 5 ~ 15 ± 0.3
Above 15 ~ 30 ± 0.4
Above 30 ~ 50 ± 0.5
Angle $\pm 0.3^\circ$

3RD.
ANGEL'S



UNITS

MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	02/27/19	FINISH	MODLE	雙層SIM卡座H3.0
CHECKED BY:	DATE	SCALE	DWG NO.	SIM-216D202-S267
Jacky Chen	02/27/19	1 : 1	PART NO.	SIM-216D202-S267
APPROVED BY:	DATE	SHEET NO.	1 of 1	
Tony Kao	02/27/19			

SIZE
A4
VER
R